



Shenzhen Tuofeng Semiconductor Technology Co., Ltd

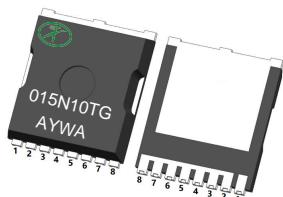
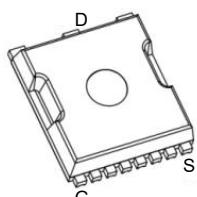
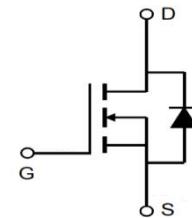
**N - CHANNEL ENHANCEMENT MODE POWER MOSFET****TF015N10TG****Features**

- V<sub>DS</sub> = 100V , I<sub>D</sub> = 310A
- R<sub>DS(ON)</sub>=1.3mΩ (typ.) @ V<sub>GS</sub>=10V
- R<sub>DS(ON)</sub>=1.8mΩ (typ.) @ V<sub>GS</sub>=6.0V

**Application**

- Power management
- Hard switched and high frequency circuits
- Uninterruptible power supply

- Low R<sub>DS(ON)</sub>
- Good stability and uniformity with high EAS High Current Capability
- Excellent package for good heat dissipation
- Fully characterized avalanche voltage and current

**Package****Top View****Top View****Schematic diagram****Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
TF015N10TG AYWA	TF015N10TG	TOLL	-	-	-

**Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)**

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DS</sub>	100	V
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current	T <sub>C</sub> =25°C	I <sub>D</sub>	310	A
	T <sub>C</sub> =100°C		200	
Pulsed Drain Current <sup>1</sup>		I <sub>DM</sub>	1200	A
Single Pulse Avalanche Energy <sup>2</sup>		EAS	1190	mJ
Total Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	380	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C
Thermal Resistance from Junction-to-Ambient <sup>3</sup>		R <sub>θJA</sub>	43	°C/W
Thermal Resistance from Junction-to-Case		R <sub>θJC</sub>	0.39	°C/W



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## N - CHANNEL ENHANCEMENT MODE POWER MOSFET

TF015N10TG

Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100	-	-	V	
Gate-body Leakage current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	$I_{\text{DSS}}$	$V_{\text{DS}} = 90\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	$\mu\text{A}$
	$T_J=100^\circ\text{C}$			-	-	100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	2.8	4.0	V	
Drain-Source on-Resistance <sup>4</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	-	1.3	1.8	$\text{m}\Omega$	
			-	1.8	2.5		
<b>Dynamic Characteristics<sup>5</sup></b>							
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	14300	-	$\text{pF}$	
Output Capacitance	$C_{\text{oss}}$		-	2120	-		
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	50	-		
Gate Resistance	$R_g$	$f=1\text{MHz}$	-	2.8	-	$\Omega$	
<b>Switching Characteristics<sup>5</sup></b>							
Total Gate Charge	$Q_g$	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 50\text{V}, I_D = 20\text{A}$	-	250	-	$\text{nC}$	
Gate-Source Charge	$Q_{gs}$		-	53	-		
Gate-Drain Charge	$Q_{gd}$		-	77	-		
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 50\text{V}, R_G = 3\Omega, I_D = 20\text{A}$	-	41	-	$\text{ns}$	
Rise Time	$t_r$		-	88	-		
Turn-off Delay Time	$t_{d(\text{off})}$		-	163	-		
Fall Time	$t_f$		-	98	-		
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 20\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	106	-	$\text{ns}$	
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	245	-	$\text{nC}$	
<b>Drain-Source Body Diode Characteristics</b>							
Diode Forward Voltage <sup>4</sup>	$V_{\text{SD}}$	$I_S = 20\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	1.2	V	
Continuous Source Current	$T_c=25^\circ\text{C}$	$I_S$	-	-	312	A	

## Notes:

- Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ .
- The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=90\text{V}, V_{\text{GS}}=10\text{V}, L=1\text{mH}, I_{\text{AS}}=50\text{A}$ .
- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
- This value is guaranteed by design hence it is not included in the production test.

### Typical Characteristics

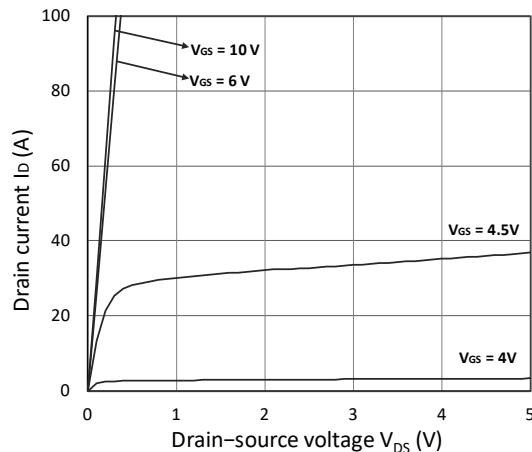


Figure 1. Output Characteristics

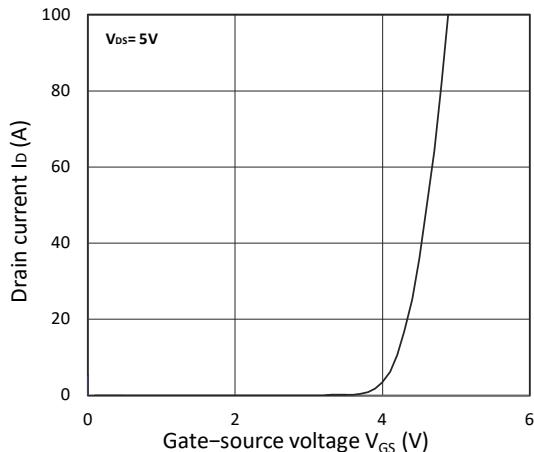


Figure 2. Transfer Characteristics

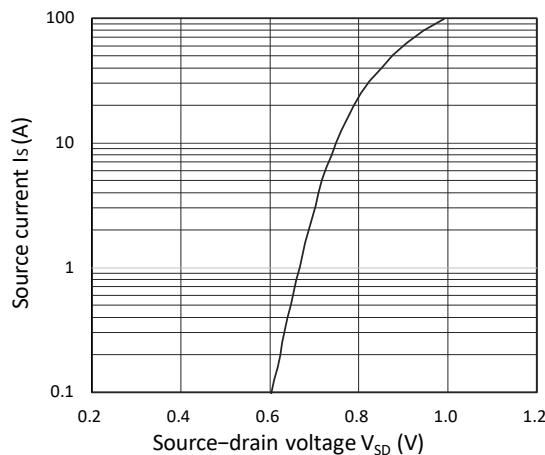


Figure 3. Forward Characteristics of Reverse

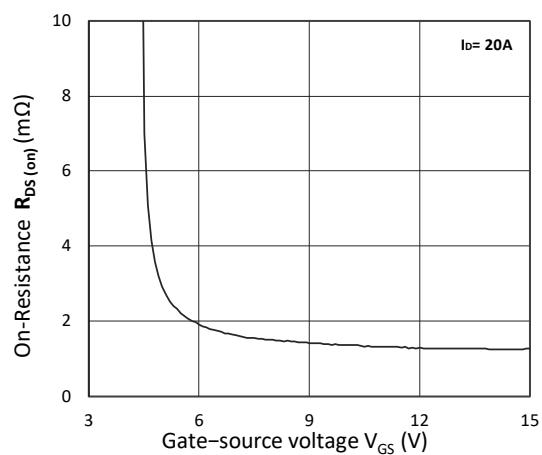


Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$

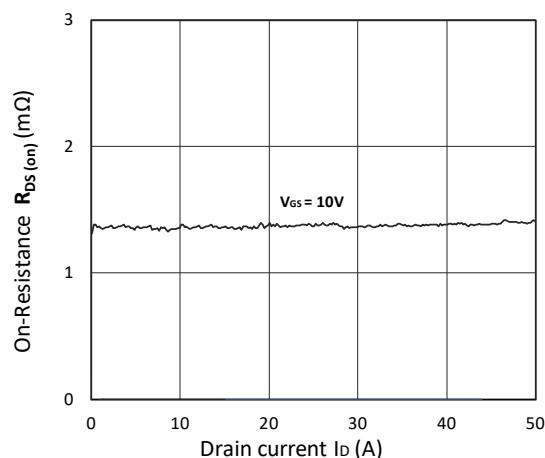


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$

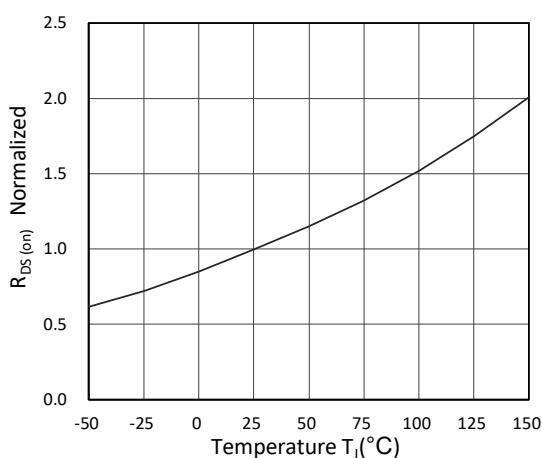


Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature

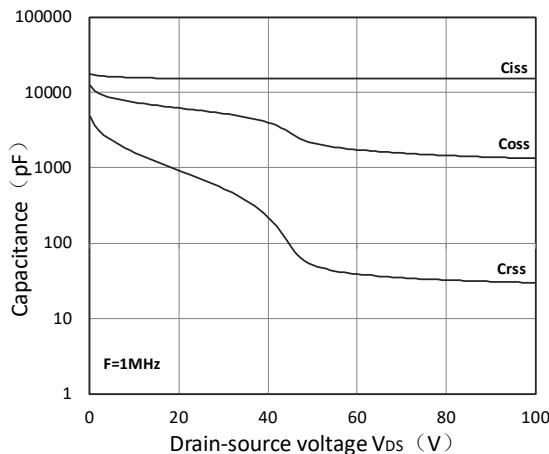


Figure 7. Capacitance Characteristics

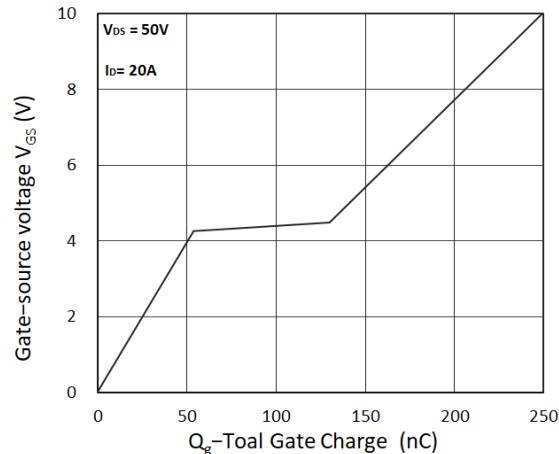


Figure 8. Gate Charge Characteristics

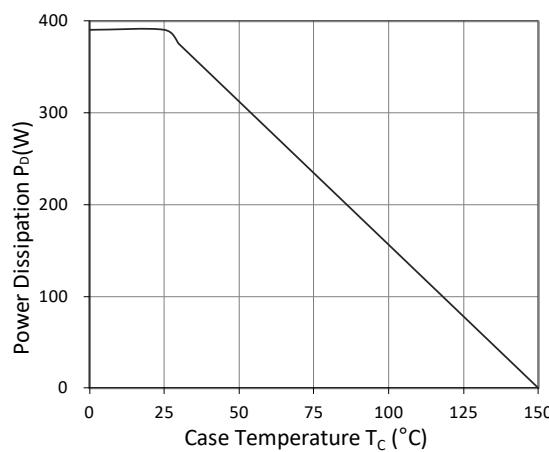


Figure 9. Power Dissipation

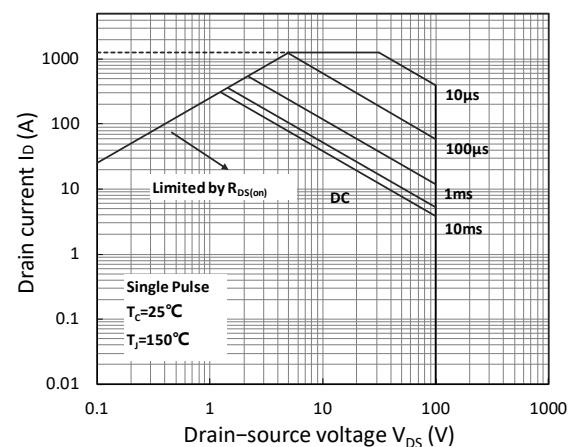


Figure 10. Safe Operating Area

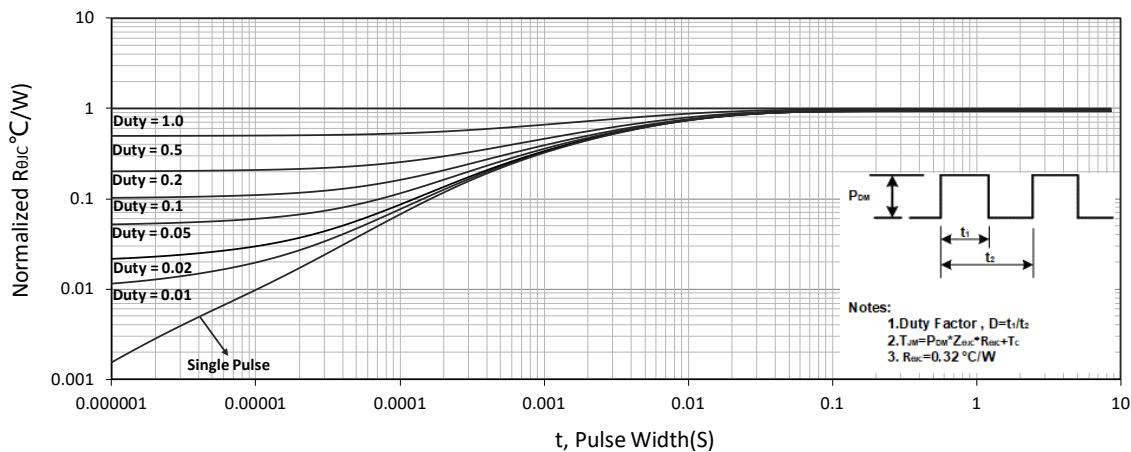


Figure 11. Normalized Maximum Transient Thermal Impedance

### Test Circuit

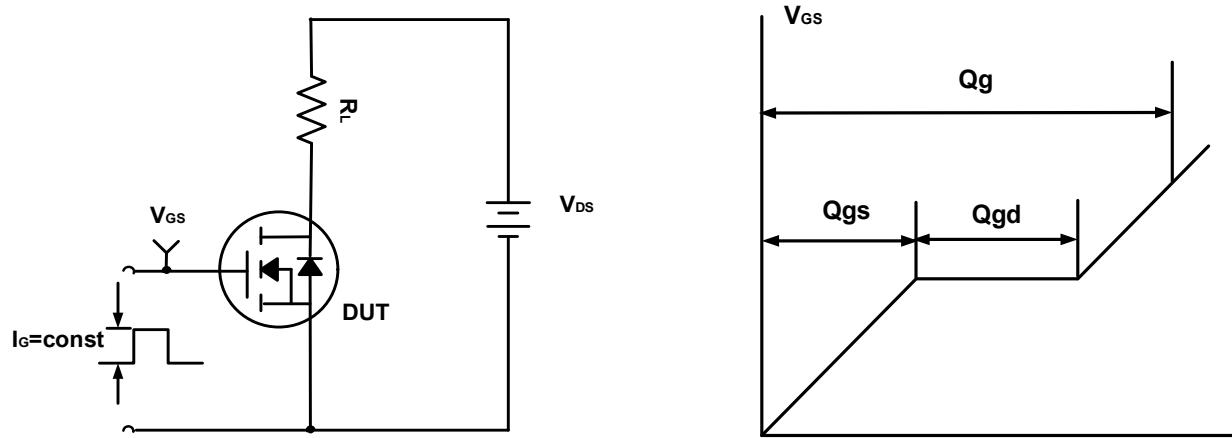


Figure A. Gate Charge Test Circuit & Waveforms

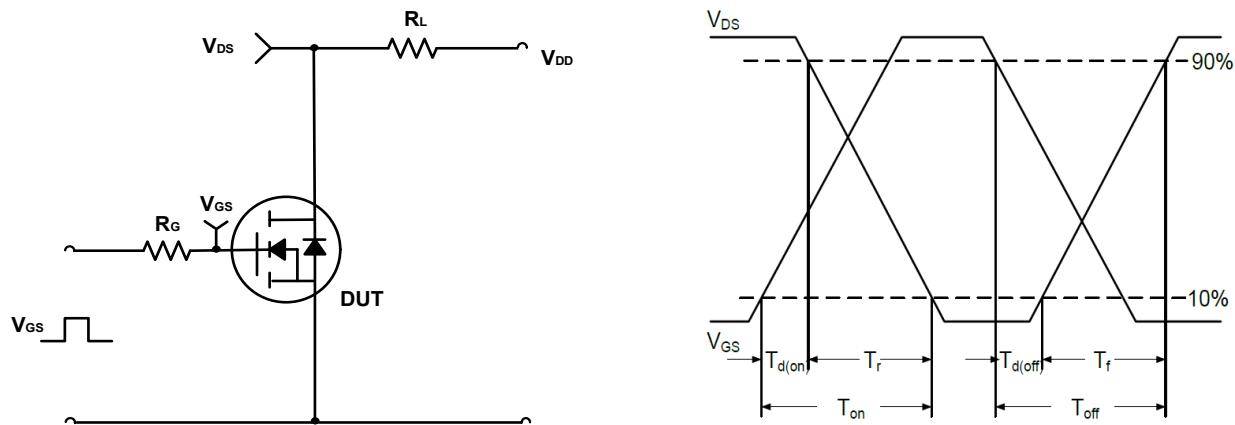


Figure B. Switching Test Circuit & Waveforms

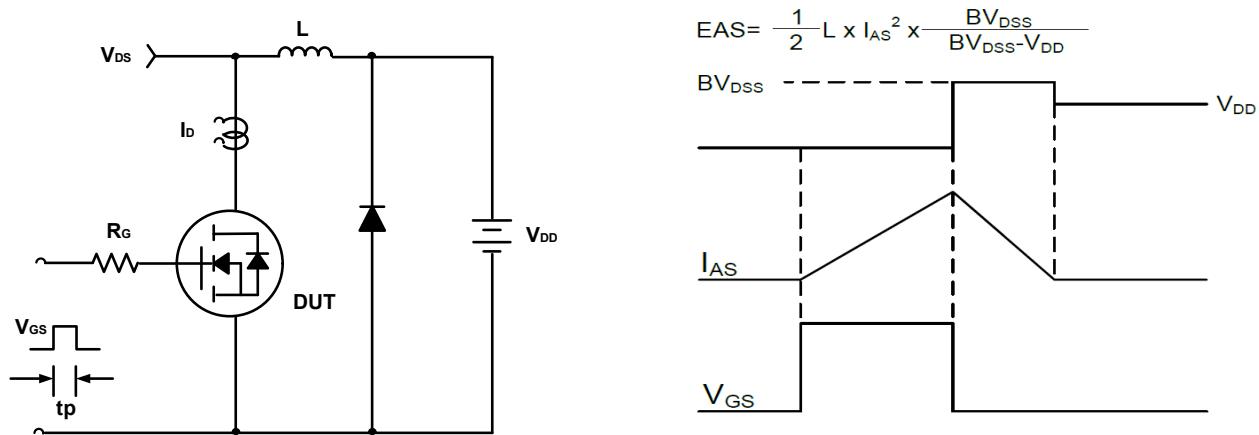


Figure C. Unclamped Inductive Switching Circuit & Waveforms

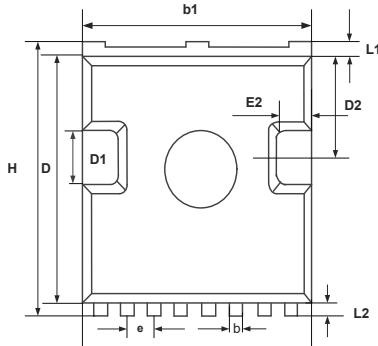


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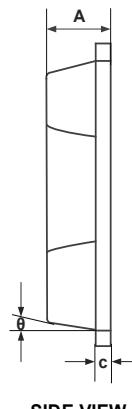
## N-CHANNEL ENHANCEMENT MODE POWER MOSFET

**TF015N10TG**

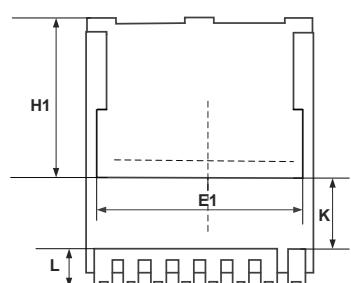
### Mechanical Dimensions for TOLL



TOP VIEW



SIDE VIEW



BOTTOM VIEW

### COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	2.20	2.40
b	0.60	0.90
b1	9.70	9.90
c	0.40	0.60
D	10.20	10.60
D1	3.10	3.50
D2	4.45	4.75
E	9.70	10.10
E1	7.80BSC	
E2	0.50	0.70
e	1.200 BSC	
H	11.45	11.90
H1	6.75 BSC	
K	3.10 REF	
L	1.70	2.10
L1	0.60	0.80
L2	0.50	0.70
$\theta$	10° REF	